

Specifications

SYSTEM

High Performance	Intel® 8th Gen Core™ i7-8700T (Frequency 2.4GHz, Turbo Boost Frequency up
Processor	to 4.0GHz), 6-Core, 12 Thread Support, 12MB SmartCache. Build-in UHD
	Graphics 630 for excellent 3D, Turbo Boost Technology 2.0, VPro and
	Hyper-Threading support
Memory type	Up to 16GB DDR4 RAM
Chipset	Intel® Q370 Chipset
DISPLAY	
GPU	Intel® UHD Graphics 630
Display Port	Resolution up to 4096x2304@60Hz
HDMI	Resolution up to 4096×2160@30Hz
DVI-D	Resolution up to 1920x1200 @ 60Hz
STORAGE	
Storage Device	1 x 2.5" Solid State Disk (SSD) 1 x mSATA Rugged Industrial NAND Flash
	mSATA Storage w/ Rugged -40/+85C High Capacity, optional Pre-loaded with
	Linux or Windows OS. 64 / 128 / 256 / 512GB /1TB / 2TB Innodisk 3MG2-P
	Series MLC SATA III 6Gb/s Flash SSD, Rated for 520 MB/sec Sequential Read;
	350 MB/sec Write Max.
ETHERNET	
Ethernet	2 x Intel Gigabit Ethernet LAN Interfaces (10/100/1000Mbps)
REAR I/O	
Display Port	1 x 20Pin DisplayPort connector (Female)
HDMI	1 x 19Pin HDMI connector (Female)
DVI-D	1 x 20Pin DVI-D connector (Female)
Ethernet	2 x RJ45 Gigabit Ethernet LAN Interfaces
Serial Port	1 x DB9 connector (RS-232)
USB Port	4 x USB3.1 Gen2 standard-A connectors
Audio Port	1 x Line-Out, 1 x MIC-In connector
DC-IN	4P Rugged Terminal connector
FRONT I/O	

Button	1 x Power Button w/Indicator LED
Indicator LED	1 x HDD LED
USB Port	2 x USB2.0 standard-A connectors
Serial Port	2 x DB9 connectors (1 x RS-232, 1 x RS232/422/485)
APPLICATIONS, OP	ERATING SYSTEM
Applications	Energy/Smart Grid/Power Plant Management, Intelligent Automation and
	manufacturing applications
Operating System	Windows 10 64bit Ubuntu16.04, Ubuntu14.04, Fedora 28
PHYSICAL	
Dimension (W x D x H)	308 x 149 x 65.2mm
Weight	3.21Kg
Chassis	Aluminum Alloy, Corrosion Resistant
Finish	Anodic aluminum oxide (Color Iron gray)
Cooling	Natural Passive Convection/Conduction. No Moving Parts
Connectors	DC-IN: PHOENIX CONTACT 1776715 RJ45
	Ethernet: RTB-19GB9J1A
	COM: FEN YING SM10-09P
	DVI : FOXCONN QH11121-DA4E-4F
	HDMI + DP : JKCR Display and HDMI Female
Ingress Protection	Dust Proof (Similar to IP50)
ENVIRONMENTAL	
MIL-STD-810G Test	Method 507.5, Procedure II (Temperature & Humidity)
	Method 516.6 Shock-Procedure V Non-Operating (Mechanical Shock)
	Method 516.6 Shock-Procedure I Operating (Mechanical Shock)
	Method 514.6 Vibration Category 24/Non-Operating (Category 20 & 24,
	Vibration)
	Method 514.6 Vibration Category 20/Operating (Category 20 & 24,
	Vibration)
	Method 501.5, Procedure I (Storage/High Temperature)
	Method 501.5, Procedure II (Operation/High Temperature)
	Method 502.5, Procedure I (Storage/Low Temperature)
	Method 502.5, Procedure II (Operation/Low Temperature)
	Method 503.5, Procedure I (Temperature shock)
Operating Temperature	-20 to 60°C (ambient with 0.7m/s airflow)

-40 to 85°C

EMC

CE and FCC compliance

Ordering Information

SR10-SCHX3

MIL-STD-810G 19" Rackmount Fanless Computer with Intel $^{\circ}$ Core i7- 8700T, 1 x DP, 1 x HDMI, 1 x DVI, 6 x USB, 12V to 24V DC-in

Dimension







